Pulse | LARSEN Antennas
A YAGEO Company

TECHNICAL DATA SHEET

Description: 860-930MHz Embedded Helical Antenna

Series: SMD Helical Antenna

PART NUMBER: W3136

Features:

- 860-930MHz
- Impedance 50 Ohm
- Plastic support helical antenna
- Length 29.5mm,
- Gain 2dBi
- SMD Mounting on PCB
- RoHS Compliant

Applications:

- 868MHz and 915MHz ISM Band Systems
- IoT systems
- Metering, Automation
- Security, surveillance
- Remote controls, toys

All dimensions are in mm / inches

Issue: 1943

RoHS COMPLIANT

For more information:

Pulse Worldwide Headquarters
15255 Innovation Drive #100
San Diego, CA 92128
USA
Tel:1-858-674-8100

Pulse/Larsen Antennas
18110 SE 34th St Bldg 2 Suite 250
Vancouver, WA 98683
USA
Tel: 1-360-944-7551

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Pulse GmbH & Do, KG
Zeppelinstrasse 15
Herrenberg, Germany
Tel: 49 7032 7806 0

Pulse (Suzhou) Wireless Products Co, Inc.
99 Huo Ju Road(#29 Bldg,4th Phase
Suzhou New District
Jiangsu Province, Suzhou 215009 PR China
Tel: 86 512 6807 9998

Description: 860-930MHz Embedded Helical Antenna

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ELECTRICAL SPECIFICATIONS

Antenna Type	Helical monopole
Frequency	860-930MHz
Nominal Impedance	50 Ω
VSWR	Max 2.5
Radiation Pattern	Omni
Gain	2 dBi
Efficiency	65%
Polarization	Linear
Power Withstanding	2W

MECHANICAL SPECIFICATIONS

Overall Length	29.5mm
Weight	2.52g
Antenna Color / Material	White
Fix system	SMD+Glue
Recommended Glue	Resinlab EP1320LV Black
Solder Paste Thickness	Min 0.15mm
MSL	3

ENVIRONMENTAL SPECIFICATIONS

Operating Temperature	-40° C~+85° C
Storage Temperature	-40° C~+85° C
RoHS Compliant	Yes

OTHER SPECIFICATIONS

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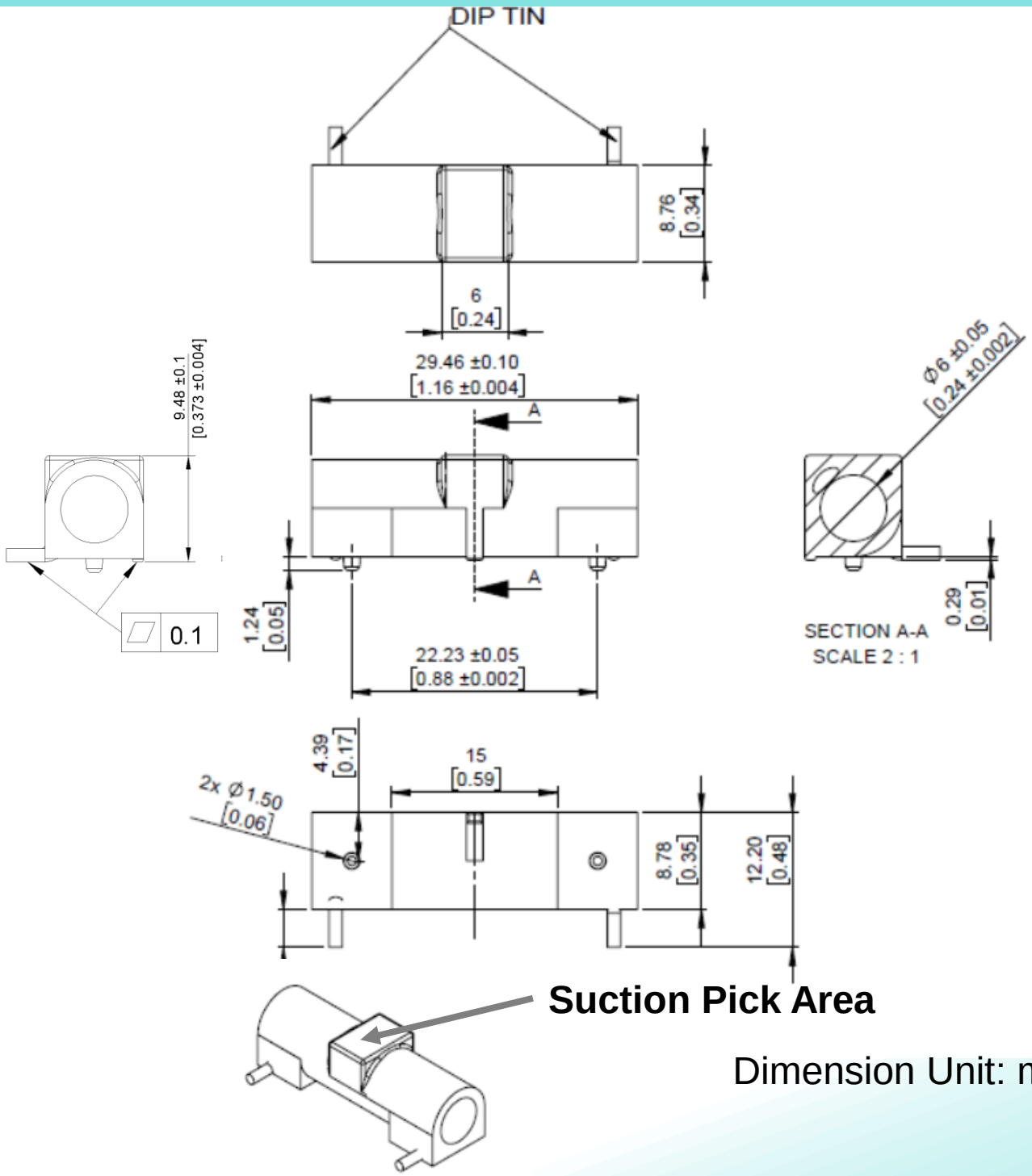
MECHANICAL DRAWING



Dimension Unit: mm[inch]

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FIX SYSTEM RECOMMENDATION

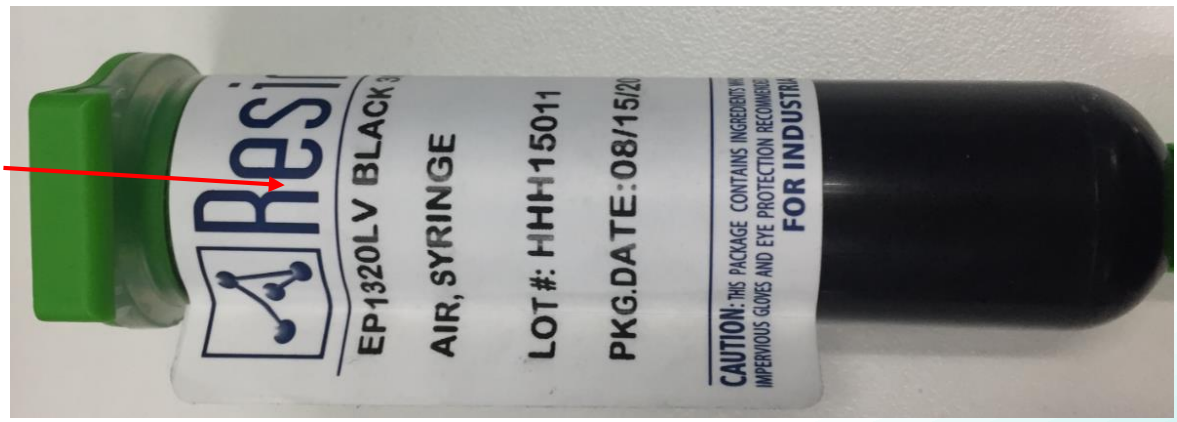
Fix system

1. SMD process
2. Solder paste thickness: minimum 0.15mm
3. Glue is required, Recommended Glue: Resinlab EP1320LV Black, usage and position see below recommended area.

Solder paste

Glue

Recommended Glue Type



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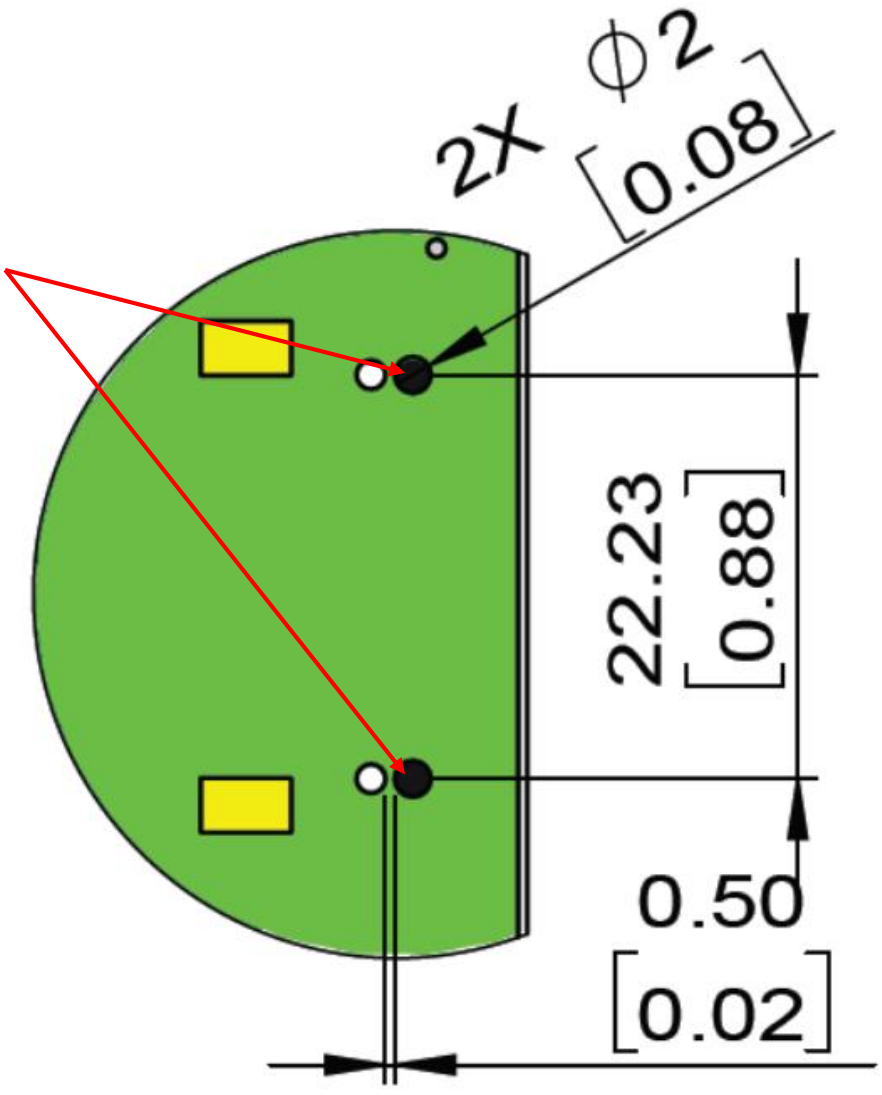
FIX SYSTEM RECOMMENDATION

Fix system

1. Glue position on PCB for recommendation

Glue position on PCB for recommendation



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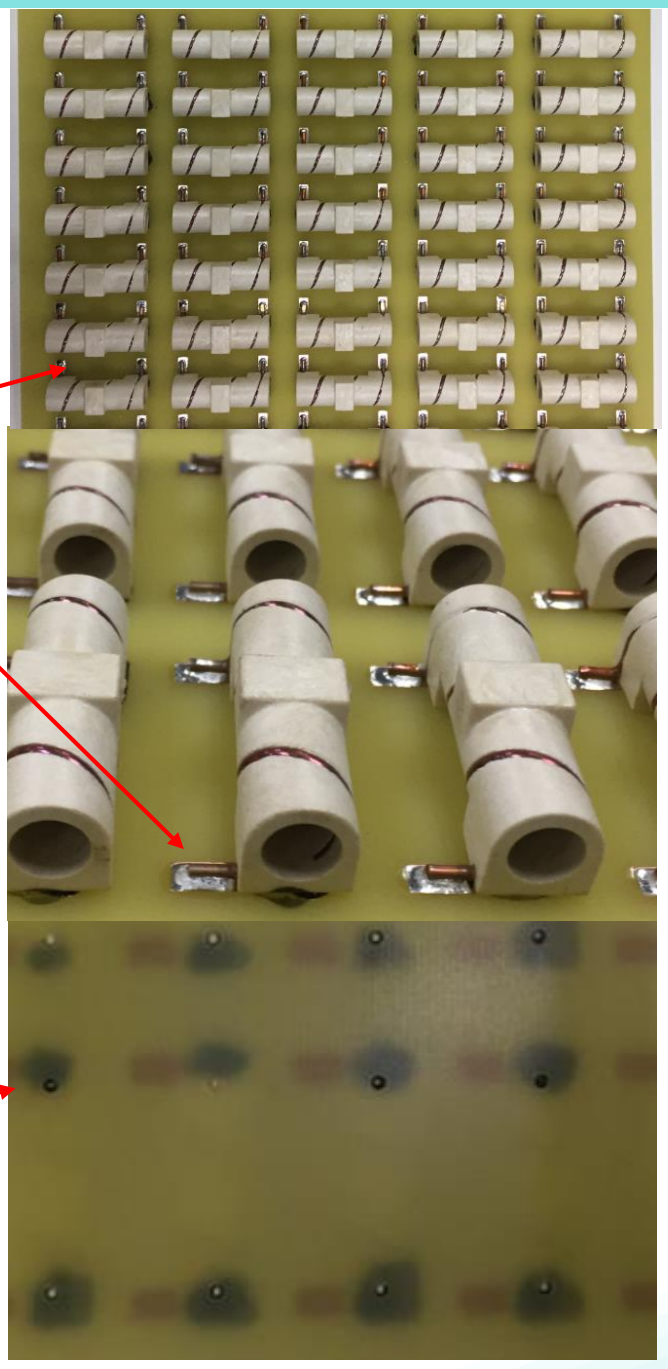
FIX SYSTEM RECOMMENDATION

Solder effect



Back view of glue area

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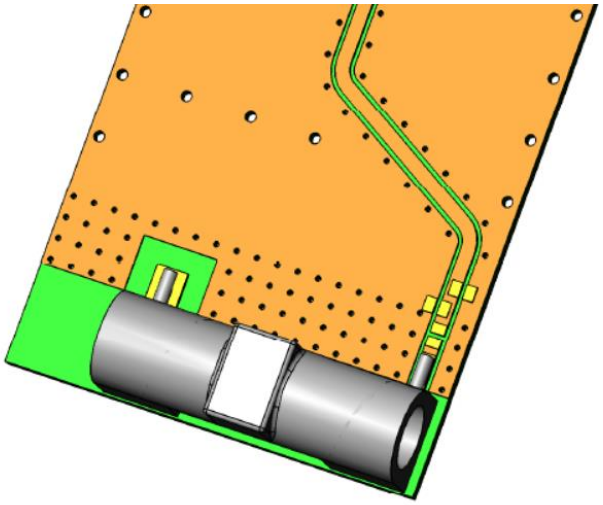
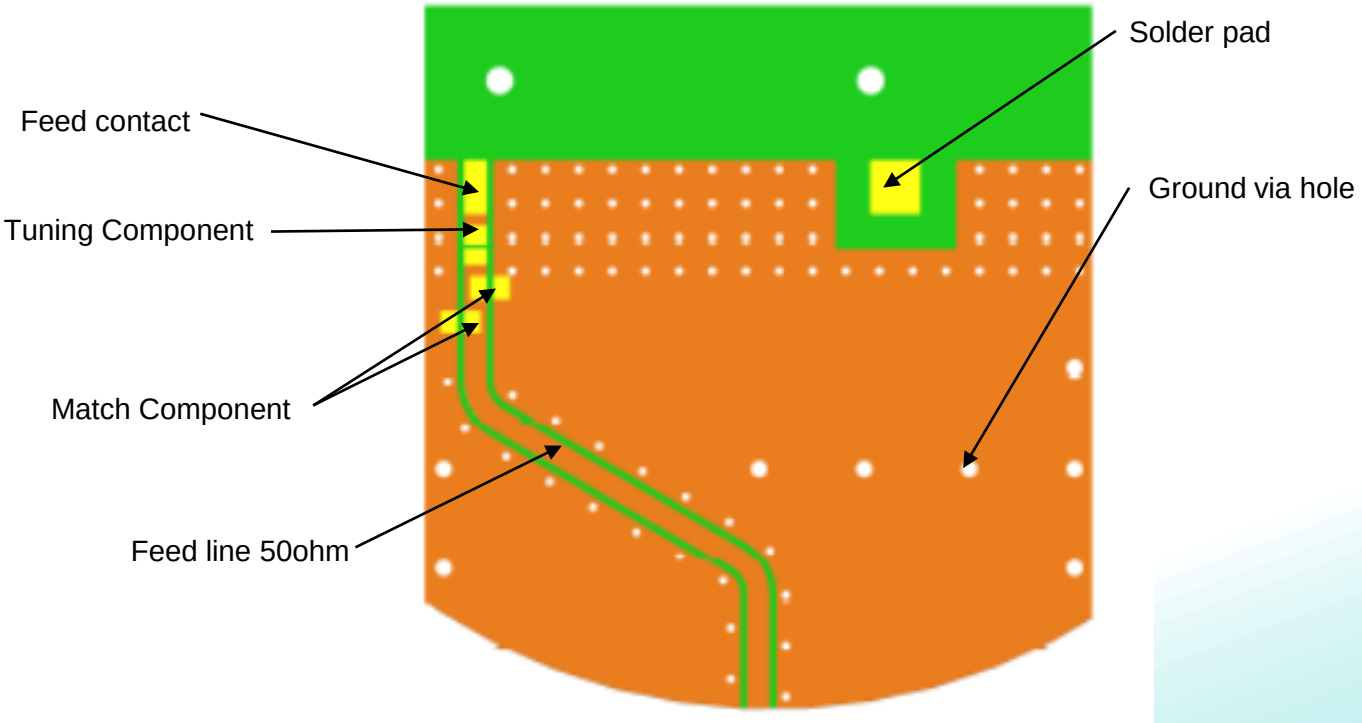
TEST SETUP

PWB Layout for W3136 SMD Helical Antenna





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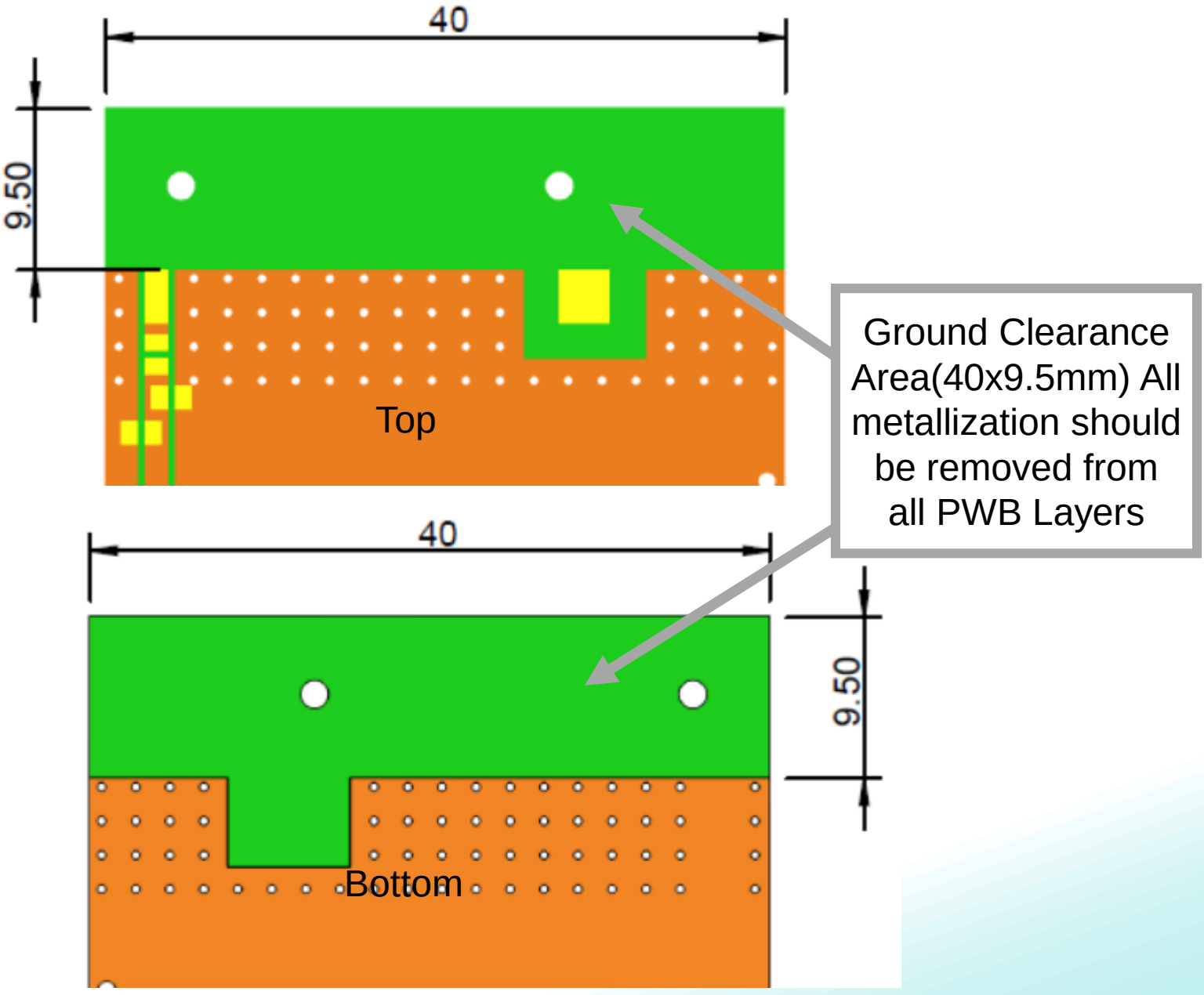
TEST SETUP

PWB ground clearance area (Top):40x9.5mm
PWB ground clearance area (Bottom):40x9.5mm



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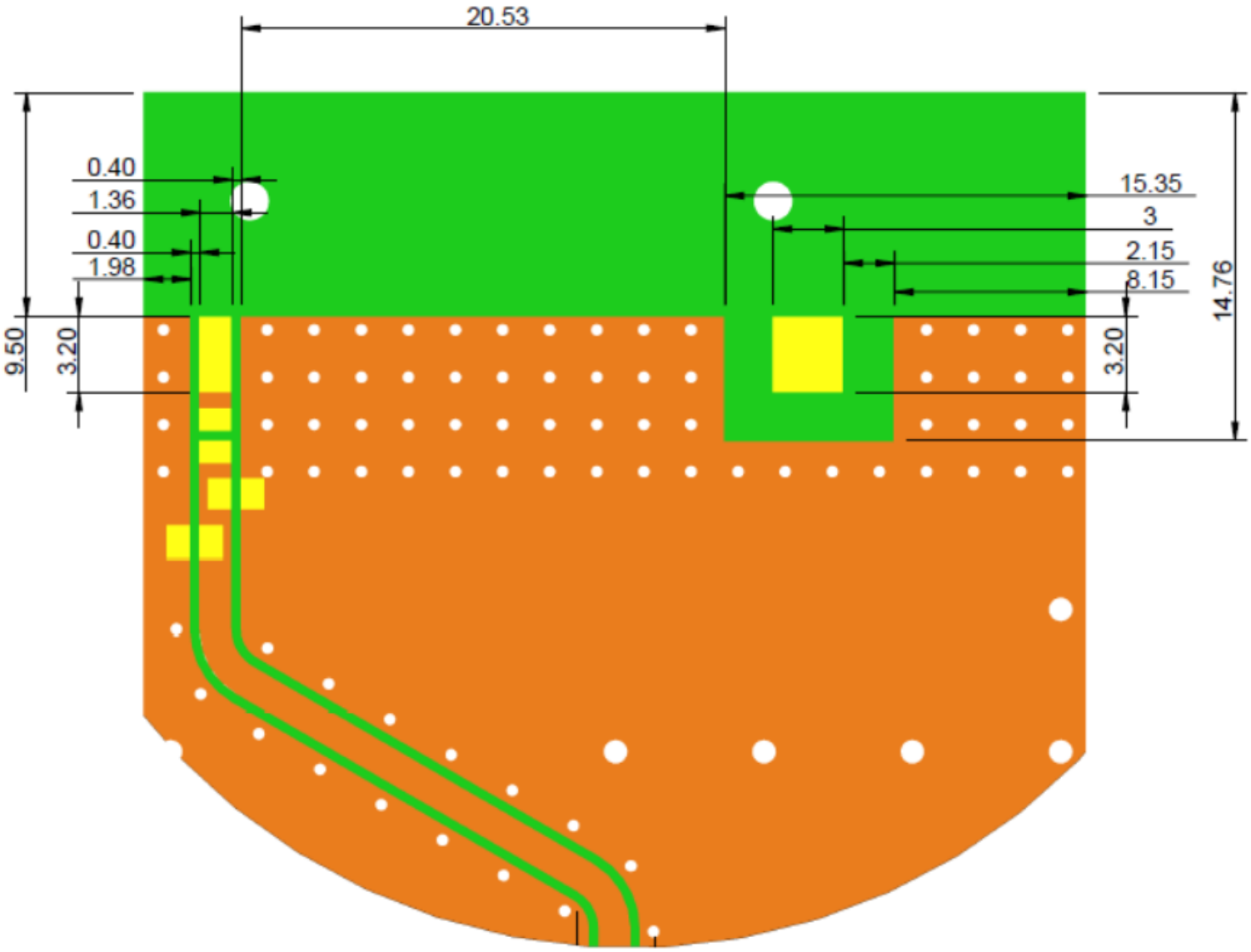
TEST SETUP

PWB Pad dimension in top copper



RoHS COMPLIANT

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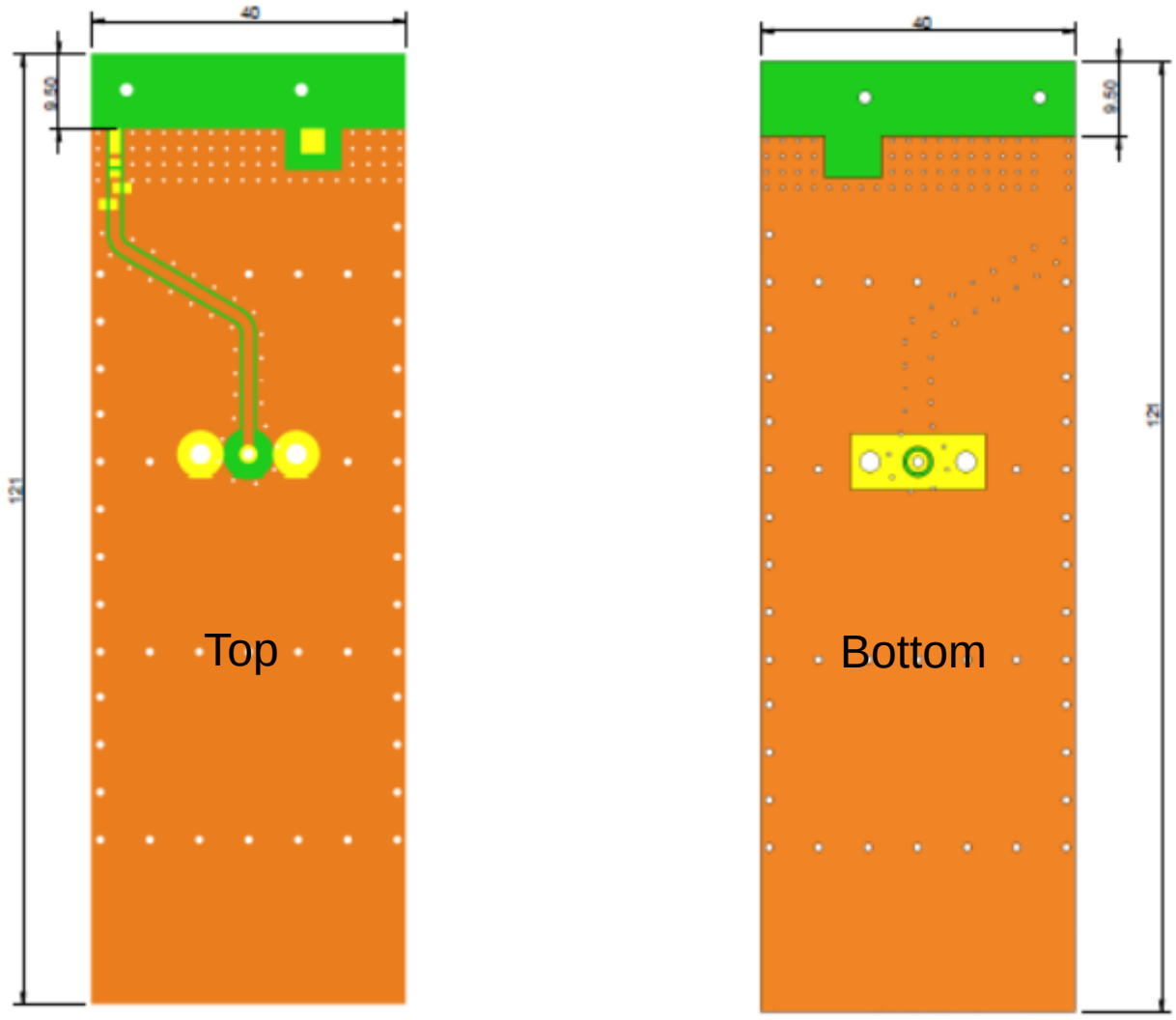
TEST SETUP

PWB Layout, Pulse PWB size:121x40mm, Thickness 1.0mm, other size boards can be used depending on customer size.



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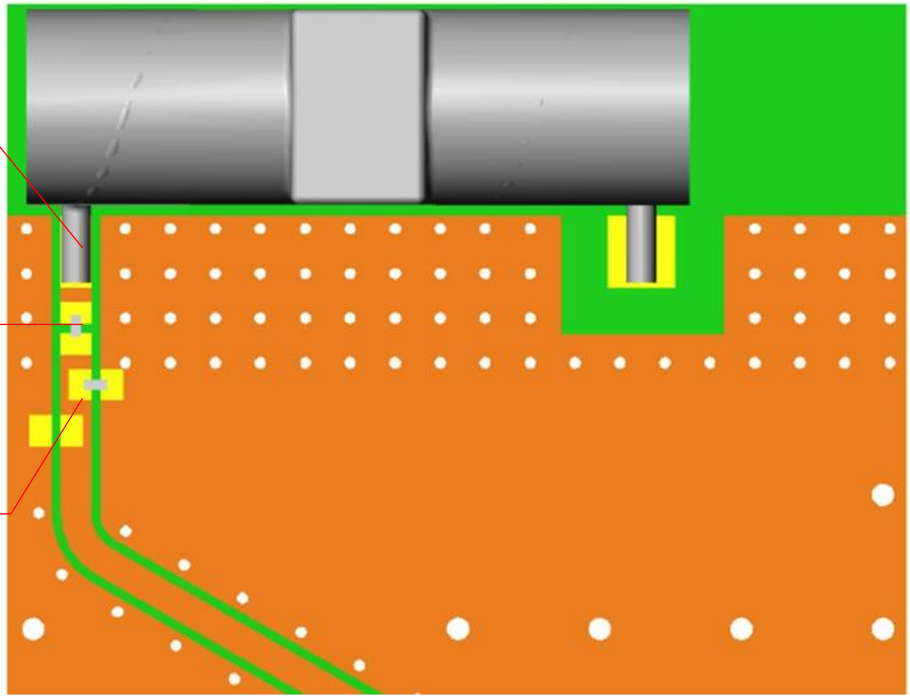
PWB Layout, Pulse PWB size:121x40mm, Thickness 1.0mm, other size boards can be used depending on customer size.

Antenna feed point

Capacitance for S11 matching , 3.6pF, series

Inductance for S11 matching , 8.2nH, shunt



Note : Exact matching and tuning components value depend on application , board size ,cover etc.

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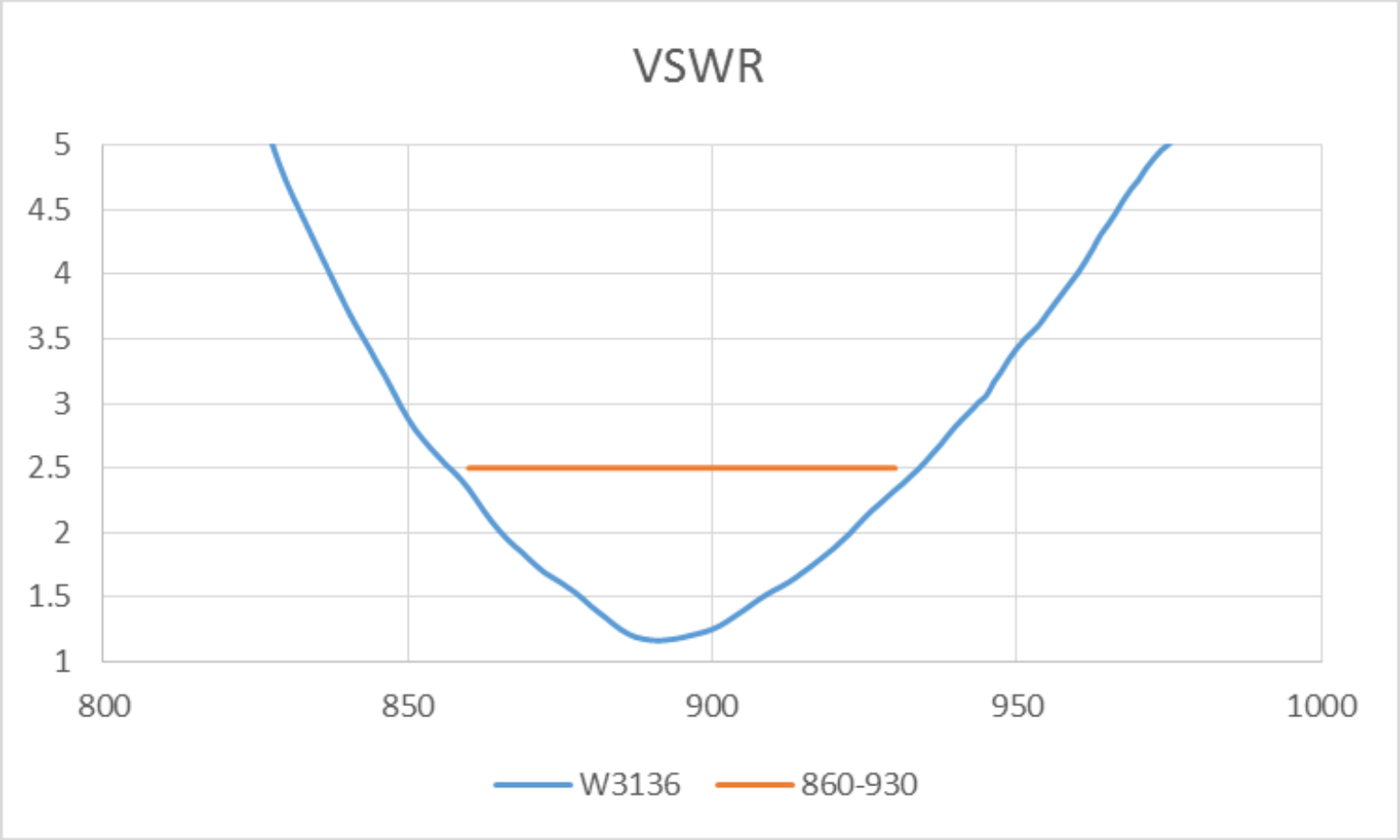
CHARTS

Measured on the 121x40mm test board with tuning and matching circuit



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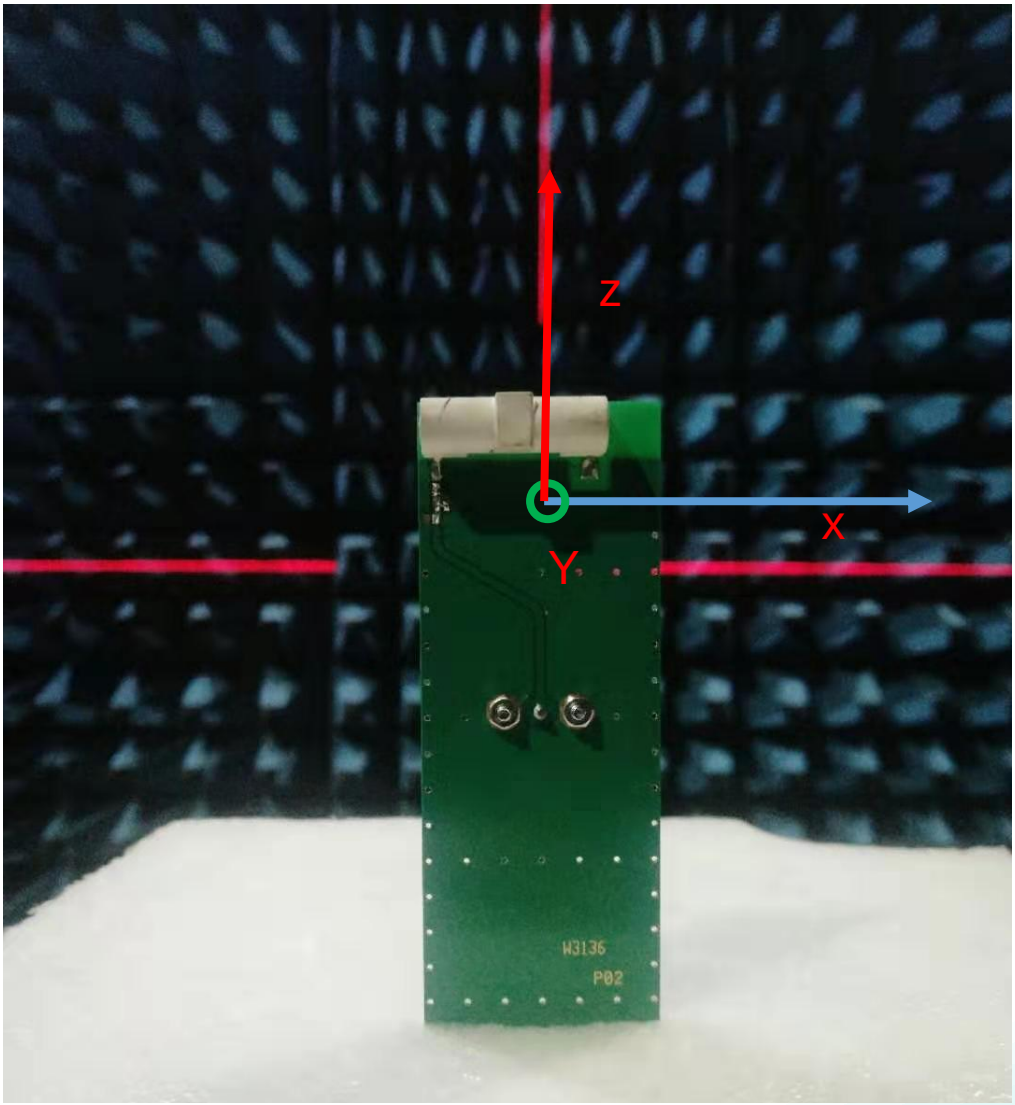
Measured on the 121x40mm test board with tuning and matching circuit.
Test in PSU China Chamber.



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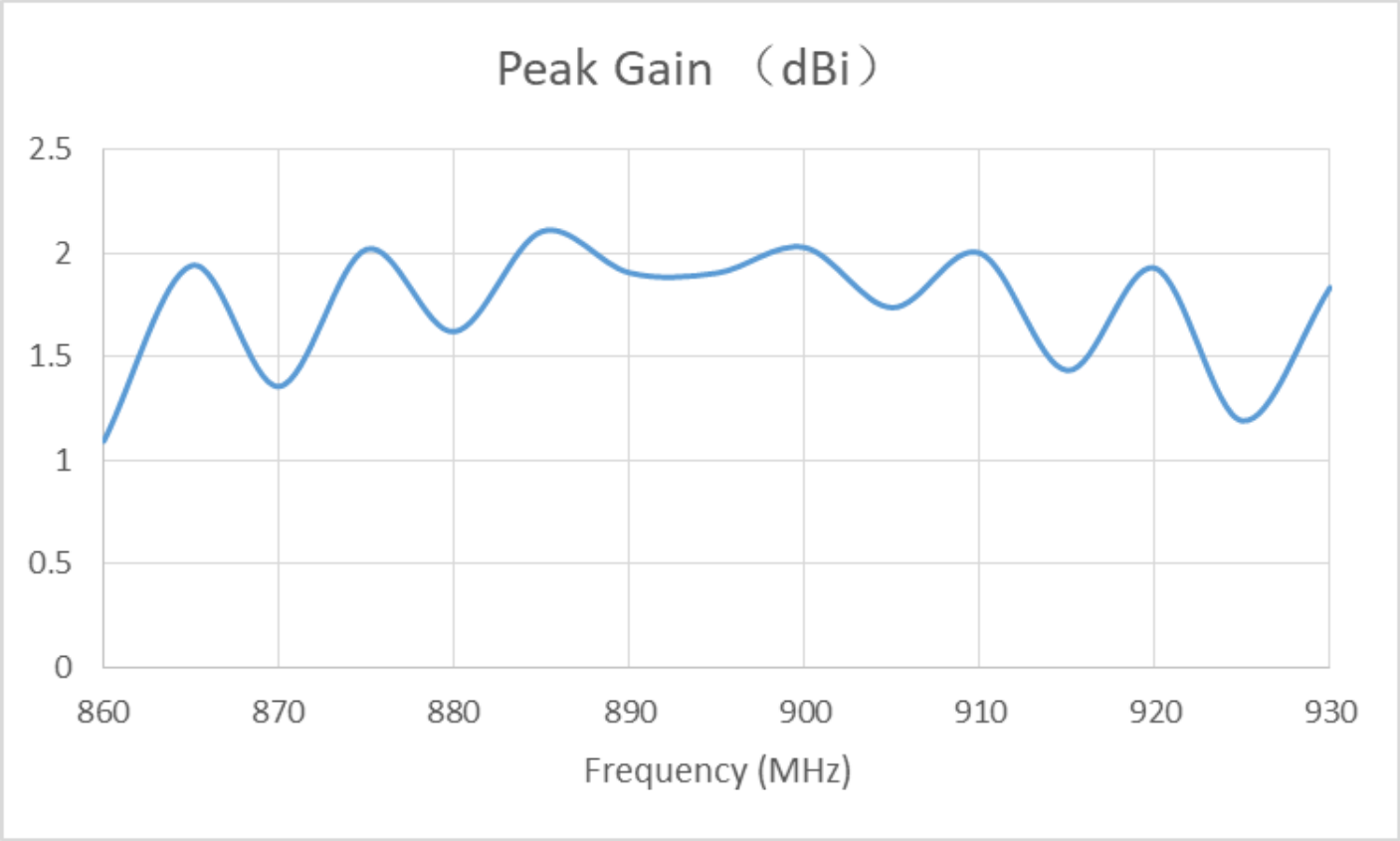

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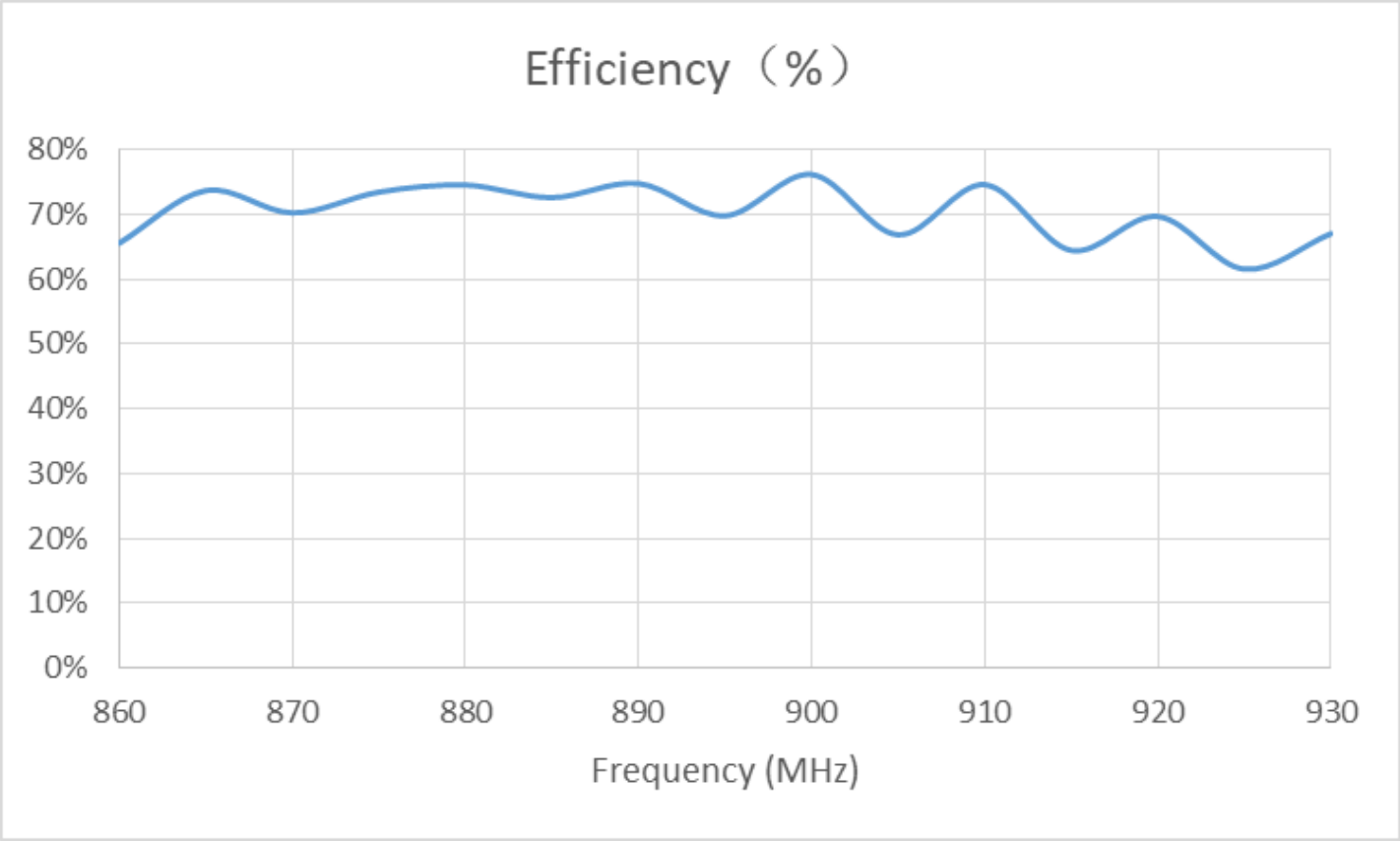

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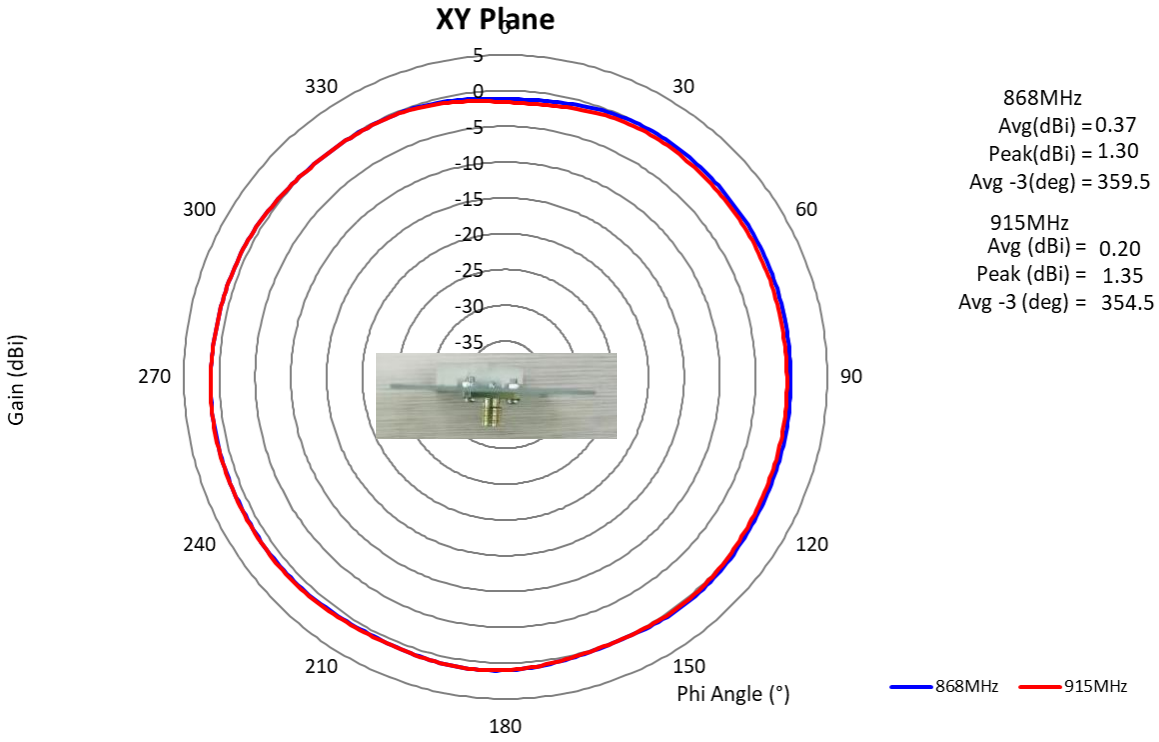
CHARTS

Typical radiation pattern in free space



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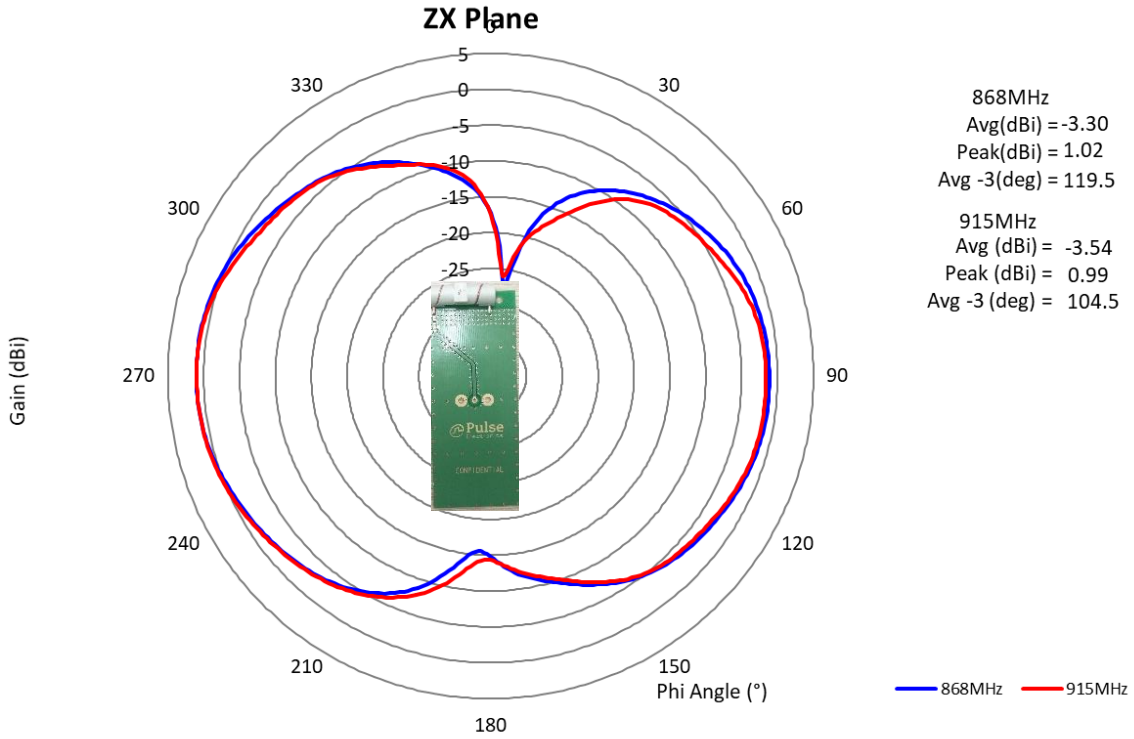

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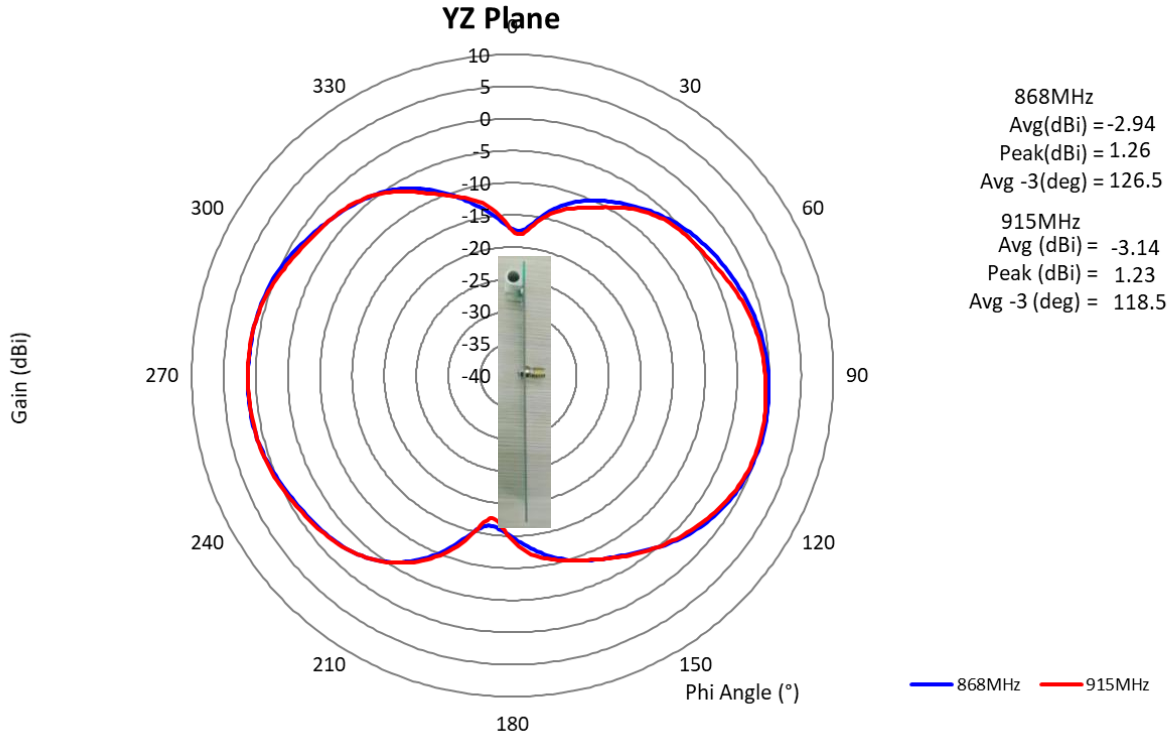

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Recommendation for reflow soldering process

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures, located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 30 sec
5	Peak temperature in reflow	230 °C for 10 seconds
6	Temperature gradient in cooling	Max -5 °C/s

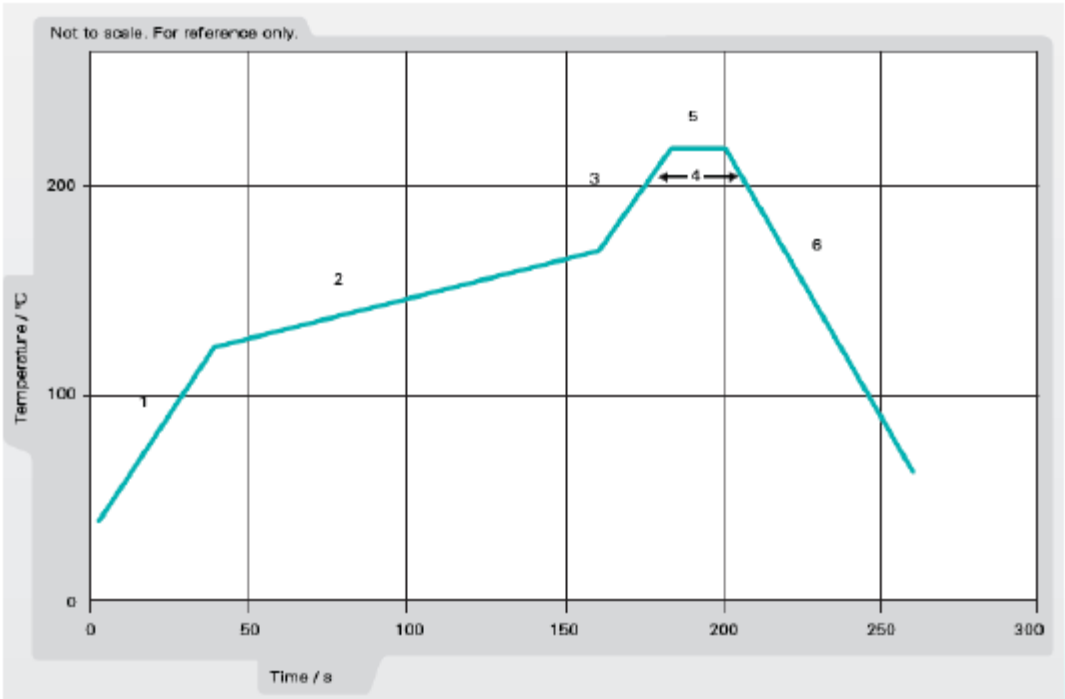

Figure 1. Minimum temperature profile recommendation for reflow soldering process

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1	Average temperature gradient in preheating	2.5 °C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3 °C/s
4	Time above 217 °C	Max 60 sec
5	Time above 230 °C	Max 50 sec
6	Time above 250 °C	Max 10 sec
7	Peak temperature in reflow	260 °C for 5 seconds
8	Temperature gradient in cooling	Max -5 °C/s

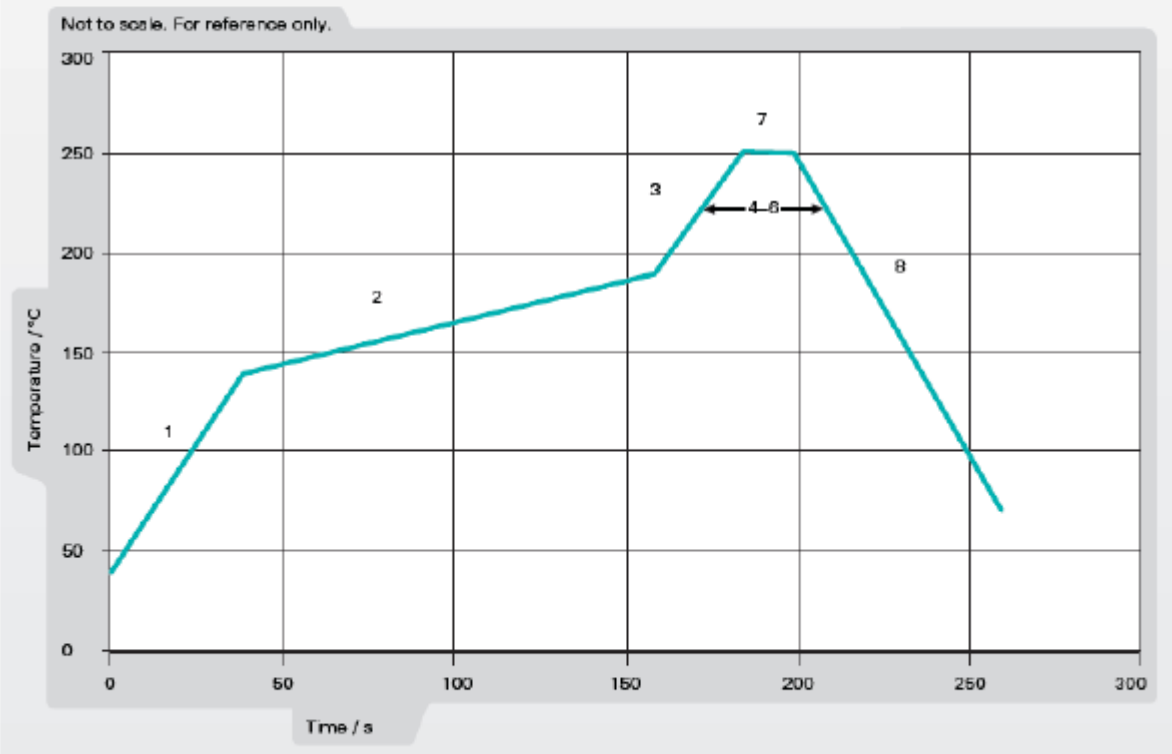

Figure 2. Maximum temperature profile recommendation for reflow soldering process

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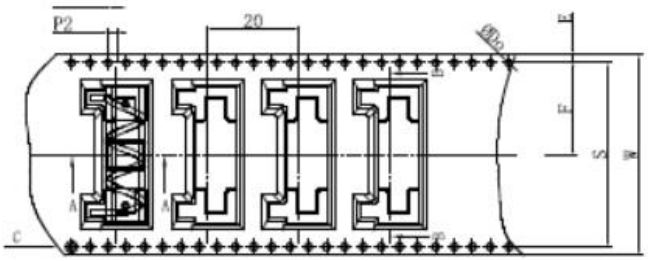
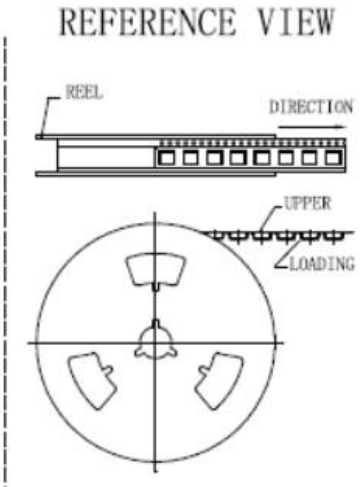
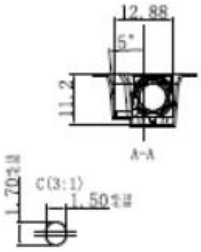
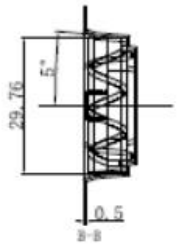
PACKAGING









5. All the size design with reference to the EIA - 481 - C - 2003.
6. Loading within 250 mm length maximum curvature is less than 1 mm (see chart).

Manufacture Data	
Total PCS	230PCS
Reel	13"/44
Package Qty	200PCS

Notes:

1. 10 side hole of the cumulative tolerance cannot be more than + / - 0.2 mm.
2. Material specifications: PS black antistatic, thickness of 0.50 mm.
3. 13 inches (100) axis reel package length: 4.6 m. (the front air bag length: 0.33 m, parts packing length: 4 m, after a period of empty packet length: 0.33 meters).
4. 13 inches (100) axis reel packaging components to the total number of stars: 230. (the front air bag star count: 15, actual packing parts the number: 200, after a period of empty bag star count: 15).

Total 200 PCS In Reel
Reel Size: 330MM[13INCH]
Total 2 PCS Reel In Package Box
Package Box Size:350x350x120mm

RoHS COMPLIANT

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001
Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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